

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPI020N06N	**Issued**	17. February 2022
MA#	MA005698546		
Package	PG-TO262-3-1	**Weight***	1576.51 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.699	0.23	0.23	2346	2346
leadframe	inorganic material	phosphorus	7723-14-0	0.255	0.02		162	
	non noble metal	iron	7439-89-6	0.851	0.05		540	
	non noble metal	copper	7440-50-8	849.682	53.90	53.97	538964	539666
wire	non noble metal	aluminium	7429-90-5	14.282	0.91	0.91	9059	9059
encapsulation	inorganic material	zincoxide	1314-13-2	5.826	0.37		3695	
	miscellaneous	miscellaneous	-	23.302	1.48		14781	
	plastics	epoxy resin	-	87.383	5.54		55428	
	inorganic material	silicondioxide	60676-86-0	466.044	29.56	36.95	295618	369522
leadfinish	non noble metal	tin	7440-31-5	15.198	0.96	0.96	9640	9640
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	145	146
solder	non noble metal	tin	7440-31-5	0.068			43	
	noble metal	silver	7440-22-4	0.085	0.01		54	
	non noble metal	lead	7439-92-1	3.258	0.21	0.22	2067	2164
heatspreader	inorganic material	phosphorus	7723-14-0	0.032			20	
	non noble metal	iron	7439-89-6	0.106	0.01		67	
	non noble metal	copper	7440-50-8	106.210	6.74	6.75	67370	67457
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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